

Test 1	Description of Visual Inspection:
	A.Receiving Inspection:
	Type and QTY of box
	Condition of box
	Type and QTY of carrier
	ESD and MSL condition
	Condition of desiccant
	Condition of Humidity Indicator Card
	Gross Weight
	Picture of received package
	Picture of goods inside

B.Part Body Inspection:	C.Terminals Inspection:	D.Mark Inspection:	E.Indent Inspection:
Package style	QTY of Oxidation	Part number	Indent Orientation
QTY Inspection	QTY of Missing terminals	Lot number	Indent Condition
QTY of cracks	QTY of Exposed Copper	Country of Origin	Indents Checking
QTY of scratches	QTY of bent terminals	Condition of mark	Checking QTY
QTY of contaminants	QTY of scratches	Colour of mark	
Dimensions of body	QTY of contaminants	Mark location	
Pictures of top side		Mark removing test	
Pictures of bottom side			

Test 2	Description of Optical Mechanical Test (3D Scan Inseption):
	The 3D scanner inspect all mechanical parameters of the devices, eg solder ball(or pins if QFP etc) size, skew, coplanarity etc...The tolerance of all mechanical parameter are set up in the machine according to the requirement in datasheet
Test 3	Description of Xray
	The use of Xrays will be used to check that there is in fact silicon inside the devices and that wire bonds are visible when possible. We will also be able to check any imperfections inside.
Test 4	2.Description of DE_CAP Inspection:
	This is a destructive analysis method used to strip the outer moulding of the device back to the silicon die. The result may need to be interpreted together with the propriety design and test information from the chip manufacturer(quite often you may find out the information from the datasheet).
Test 5	Description of Unpowered BEST Test
	The BEST test is to test the electrical parameters of every pin to pin, eg current, voltage, diode resistivity, silicon connectivity.
	Curve Tracing is a valuable and powerful tool for failure analysis and reliability engineering. By the test,it is easy to identify the counterfeit or ESD/MSD damaged devices.The devices are tested in a controlled profile and form up a curve trace. Good devices should show exactly same curve trace or within the tolerance indicated in datasheet.
Test 6	Description of Powered BEST Test
	Same as Test 3 although Power is actually added to the device to "Switch on" the device.
Test 7	Description of I/O Silicon and Register Test
	This test is based around Boundary Scan testing were the internal code of the device will be verified and the registers checked for continuity though the terminations and silicon inside the device
Test 8	Description of programming Test:
	This test is mainly to test flash/memory chip. The programming machine performs a series of steps of erase, blank-check, programming, check-sum, erase, blank-check etc to verify if the chip functions.
Test 9	Description of KEY functional test:
	The test equipment to power up and drive this device, and simulate the device's working condition on PCBA to test major key functions of the device. The test accuracy is high. Leadtime might be a bit longer due to socket making.
Test 10	Description of Solderability Test
	This test will be used ONLY for NON-BGA devices and is in line with Jeduc standard for dip solderability test. Images will be presented of the device termiantiosn after the recommended test is completed with the results.
Test 11	Description of XRF Analysis
	This test will be able to confirm the RoHS and non-RoHS status of parts, check the alloy of the solder terminations.